

IN THE CLAIMS

Please amend the claims as follows:

Claim 1 (Original): A hot-melt adhesive composition containing as a main component a crystalline compound having a melting temperature of 50 to 300°C, said composition having a melting temperature width of not more than 30°C and having a melt viscosity of not more than 0.1 Pa·s at a melting temperature of the composition.

Claim 2 (Original): The hot-melt adhesive composition as claimed in claim 1, wherein the crystalline compound is an organic compound composed of elements of C, H and O only and having a molecular weight of not more than 1000.

Claim 3 (Currently Amended): The hot-melt adhesive composition as claimed in claim 1 ~~or 2~~, wherein the total of an alkali metal ion content and a heavy metal ion content in the composition is not more than 100 ppm.

Claim 4 (Currently Amended): The hot-melt adhesive composition as claimed in ~~any one of claims 1 to 3~~ claim 1, wherein the crystalline compound is an aliphatic compound or an alicyclic compound.

Claim 5 (Currently Amended): The hot-melt adhesive composition as claimed in ~~any one of claims 1 to 3~~ claim 1, wherein the crystalline compound is a compound having a steroid skeleton and/or a hydroxyl group in a molecule or a derivative thereof (except an ester derivative).

Claim 6 (Currently Amended): The hot-melt adhesive composition as claimed in any ~~one of claims 1 to 5~~ claim 1, which contains a surface tension modifier.

Claim 7 (Original): The hot-melt adhesive composition as claimed in claim 6, wherein the surface tension modifier is at least one substance selected from the group consisting of fluorine-based surface active agents having a fluorinated alkyl group and polyether alkyl-based surface active agents having an oxyalkyl group.

Claim 8 (Currently Amended): The hot-melt adhesive composition as claimed in any ~~one of claims 1 to 7~~ claim 1, which has properties that a bond strength A (MPa) at a temperature of  $25 \pm 2^\circ\text{C}$  that is given when a wafer and a glass substrate are bonded using the composition and a bond strength B (MPa) at a temperature lower than the melting temperature of the composition by  $20^\circ\text{C}$  that is given when they are bonded using the composition satisfy the following relational expression (1):

$$0 < A - B < 0.5 \quad (1).$$

Claim 9 (Currently Amended): The hot-melt adhesive composition as claimed in any ~~one of claims 1 to 8~~ claim 1, which is in the form of a tablet.

Claim 10 (Original): A hot-melt adhesive kit comprising the tablet hot-melt adhesive composition of claim 9, a surface treatment agent and a cleaning liquid.